

*Functional Safety Information*

**LM5156, LM5156-Q1, LM51561, LM51561-Q1,  
LM5156H, LM5156H-Q1, LM51561H, LM51561H-Q1  
and LM34966-Q1 Functional Safety FIT Rate and  
FMD**



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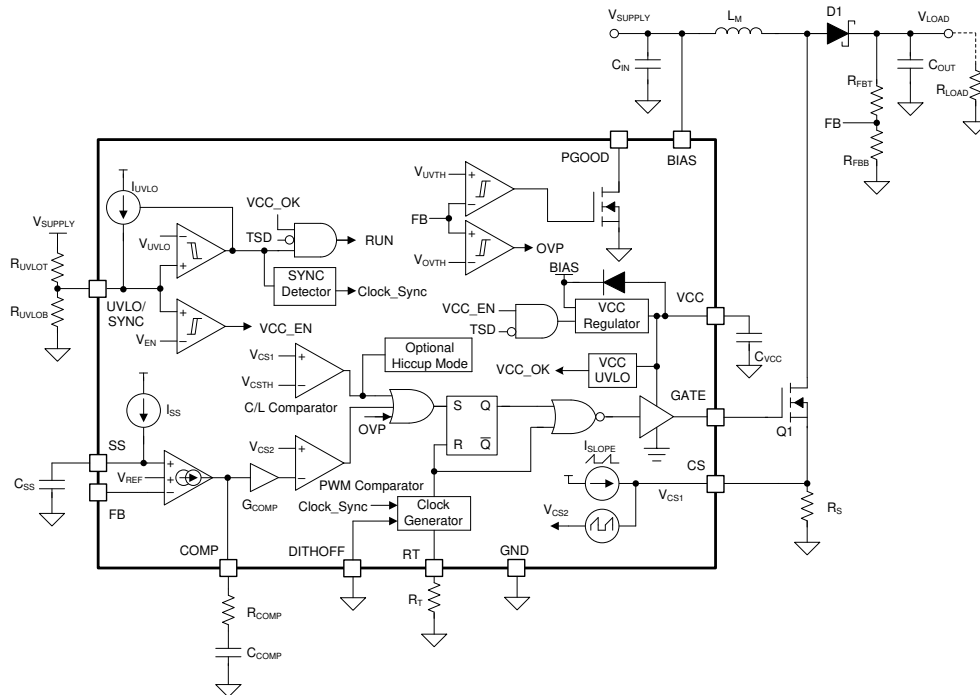
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## 1 Overview

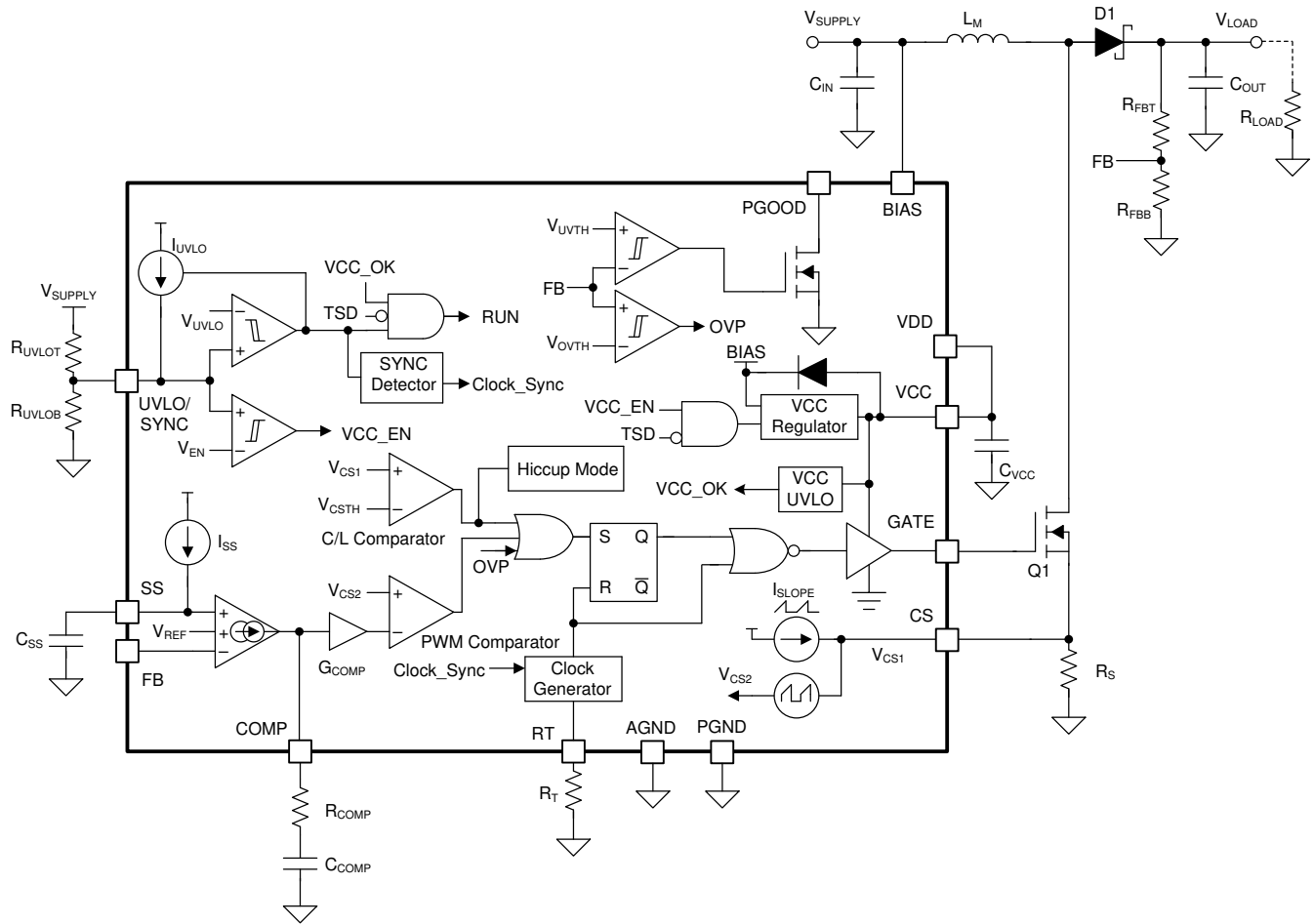
This document contains information for LM5156, LM5156-Q1, LM51561, LM51561-Q1, LM5156H, LM5156H-Q1, LM51561H, LM51561H-Q1 and LM34966-Q1 (WSON and HTSSOP packages) to aid in a functional safety system design. Information provided are:

- 
- Functional Safety Failure In Time (FIT) rates of the semiconductor component estimated by the application of industry reliability standards
- Component failure modes and their distribution (FMD) based on the primary function of the device

Figure 1-1 and Figure 1-2 show the device functional block diagrams for reference.



**Figure 1-1. Functional Block Diagram (LM5156xH, LM5156xH-Q1)**



**Figure 1-2. Functional Block Diagram (LM34966-Q1)**

The LM5156, LM5156-Q1, LM51561, LM51561-Q1, LM5156H, LM5156H-Q1, LM51561H, LM51561H-Q1 and LM34966-Q1 were developed using a quality-managed development process, but were not developed in accordance with the IEC 61508 or ISO 26262 standards.

## 2 Functional Safety Failure In Time (FIT) Rates

This section provides Functional Safety Failure In Time (FIT) rates for LM5156, LM5156-Q1, LM51561, LM51561-Q1 (package of WSON) based on two different industry-wide used reliability standards:

- [Table 2-1](#) provides FIT rates based on IEC TR 62380 / ISO 26262 part 11
- [Table 2-2](#) provides FIT rates based on the Siemens Norm SN 29500-2

**Table 2-1. Component Failure Rates per IEC TR 62380 / ISO 26262 Part 11**

FIT IEC TR 62380 / ISO 26262	FIT (Failures Per 10 <sup>9</sup> Hours)
Total Component FIT Rate	6
Die FIT Rate	3
Package FIT Rate	3

The failure rate and mission profile information in [Table 2-1](#) comes from the Reliability data handbook IEC TR 62380 / ISO 26262 part 11:

- Mission Profile: Motor Control from Table 11
- Power dissipation: 250 mW
- Climate type: World-wide Table 8
- Package factor (lambda 3): Table 17b
- Substrate Material: FR4
- EOS FIT rate assumed: 0 FIT

**Table 2-2. Component Failure Rates per Siemens Norm SN 29500-2**

Table	Category	Reference FIT Rate	Reference Virtual T <sub>J</sub>
5	CMOS/BICMOS ASICs Analog & Mixed HV >50V supply	30 FIT	75°C

The Reference FIT Rate and Reference Virtual T<sub>J</sub> (junction temperature) in [Table 2-2](#) come from the Siemens Norm SN 29500-2 tables 1 through 5. Failure rates under operating conditions are calculated from the reference failure rate and virtual junction temperature using conversion information in SN 29500-2 section 4.

### 3 Functional Safety Failure In Time (FIT) Rates

This section provides Functional Safety Failure In Time (FIT) rates for LM5156H, LM5156H-Q1, LM51561H, LM51561H-Q1 and LM34966-Q1 (package of HTSSOP) based on two different industry-wide used reliability standards:

- [Table 3-1](#) provides FIT rates based on IEC TR 62380 / ISO 26262 part 11
- [Table 3-2](#) provides FIT rates based on the Siemens Norm SN 29500-2

**Table 3-1. Component Failure Rates per IEC TR 62380 / ISO 26262 Part 11**

FIT IEC TR 62380 / ISO 26262	FIT (Failures Per 10 <sup>9</sup> Hours)
Total Component FIT Rate	12
Die FIT Rate	4
Package FIT Rate	8

The failure rate and mission profile information in [Table 3-1](#) comes from the Reliability data handbook IEC TR 62380 / ISO 26262 part 11:

- Mission Profile: Motor Control from Table 11
- Power dissipation: 250 mW
- Climate type: World-wide Table 8
- Package factor (lambda 3): Table 17b
- Substrate Material: FR4
- EOS FIT rate assumed: 0 FIT

**Table 3-2. Component Failure Rates per Siemens Norm SN 29500-2**

Table	Category	Reference FIT Rate	Reference Virtual T <sub>J</sub>
5	CMOS/BICMOS ASICs Analog & Mixed HV >50V supply	30 FIT	75°C

The Reference FIT Rate and Reference Virtual T<sub>J</sub> (junction temperature) in [Table 3-2](#) come from the Siemens Norm SN 29500-2 tables 1 through 5. Failure rates under operating conditions are calculated from the reference failure rate and virtual junction temperature using conversion information in SN 29500-2 section 4.

## 4 Failure Mode Distribution (FMD)

The failure mode distribution estimation for LM5156, LM5156-Q1, LM51561, LM51561-Q1, LM5156H, LM5156H-Q1, LM51561H, LM51561H-Q1 and LM34966-Q1 (WSON and HTSSOP packages) in [Table 4-1](#) comes from the combination of common failure modes listed in standards such as IEC 61508 and ISO 26262, the ratio of sub-circuit function size and complexity and from best engineering judgment.

The failure modes listed in this section reflect random failure events and do not include failures due to misuse or overstress.

**Table 4-1. Die Failure Modes and Distribution**

Die Failure Modes	Failure Mode Distribution (%)
No Output Voltage	60%
Output not in specification – voltage or timing	30%
Gate Driver stuck on	5%
Power Good – False Trip or Failure to Trip	5%

## 5 Revision History

NOTE: Page numbers for previous revisions may differ from page numbers in the current version.

Changes from Revision * (June 2020) to Revision A (September 2020)	Page
• Added LM34966-Q1 (HTSSOP).....	<a href="#">2</a>

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